

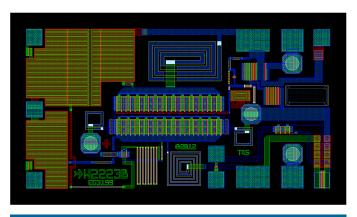


### **Applications**

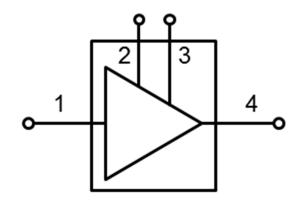
- Repeaters
- Mobile Infrastructure
- Defense/Aerospace
- LTE / WCDMA / EDGE / CDMA
- General Purpose Wireless
- · IF amplifier, RF driver amplifier
- Military Communications

#### **Product Features**

- Frequency Range: 0.05 4.0 GHz
- NF: 2.1 dB (@ 1.9 GHz)
- Output IP3: +36 dBm (@1.9 GHz, 4 dBm/tone Pout)
- P1dB:+21 dBm (@ 1.9 GHz)
- Small Signal Gain: 14 dB (@ 1.9 GHz)
- +5V Single Supply, 85 mA Current
- Chip Dimensions: 1.49 x 0.85 x 0.085 mm



#### **Functional Block Diagram**



## **General Description**

The TriQuint TGA4928 is a high linearity Low Noise Amplifier. The amplifier is fabricated using TriQuint's TQPED process. It is internally matched and only requires an external RF choke and blocking/bypass capacitors for operation from a single +5V supply. The internal active bias circuit also enables stable operation over bias and temperature variations.

The TGA4928 covers the 0.05–4.0 GHz frequency band and is targeted for wireless infrastructure or other applications requiring high linearity and/or low noise figure.

Die attach should be accomplished with conductive epoxy only. Eutectic attach is not recommended.

Lead-free and RoHS compliant

Evaluation Boards are available upon request.

# **Pad Configuration**

Pad No.	Symbol	
1	RF Input	
2	(Opt.) External Cap.	
3	(Opt.) External Cap.	
4	RF Output / Bias	

# **Ordering Information**

Part	ECCN	Description
TGA4928	EAR99	High Linearity LNA Gain Block



### **Absolute Maximum Ratings**

Parameter	Value
Drain Voltage (V <sub>D</sub> )	7.0 V
Power Dissipation, 85 °C (PDISS)	1.2 W
Input Power, CW, 50 Ω, T=25 °C (P <sub>IN</sub> )	23 dBm
Storage Temperature	-55 to 150 ℃

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied.

# **Recommended Operating Conditions**

Parameter	Value	
Drain Voltage (V <sub>D</sub> )	5 V	
Drain Current (IDQ)	85 mA	

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all operating conditions.

# **Electrical Specifications**

Test conditions unless otherwise noted: 25 °C, V<sub>D</sub> = 5 V, tested using EVB application circuit shown on page 7

Parameter	Min	Typical	Max	Units
Operational Frequency Range	0.05	1.9	4.0	GHz
Small Signal Gain		14		dB
Input Return Loss		15		dB
Output Return Loss		15		dB
Noise Figure		2.1		dB
Output Power at 1 dB Gain Compression		21		dBm
Output IP3 (Pout=4 dBm/tone)		36		dBm
Gain Temperature Coefficient		-0.004		dB/°C
Noise Figure Temperature Coefficient		0.007		dB/°C

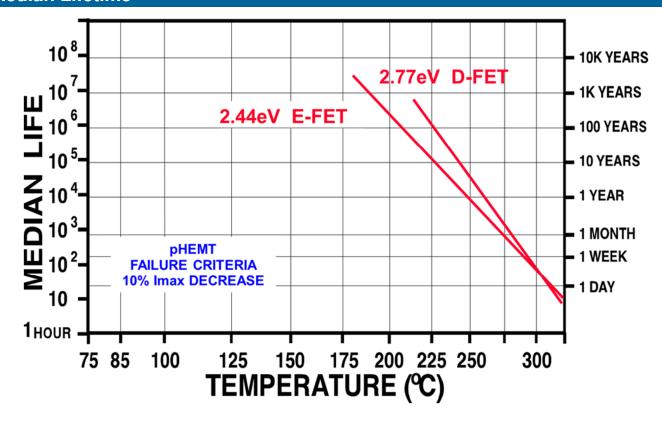


## **Thermal and Reliability Information**

Parameter	Test Conditions	Value	Units
Thermal Resistance (θ <sub>JC</sub> ) (1)	V 5V L 05 A D 0 405 W	36.6	ºC/W
Channel Temperature (T <sub>CH</sub> )	$V_D = 5 \text{ V}, I_{DQ} = 85 \text{ mA}, P_{DISS} = 0.425 \text{ W}, I_{base} = 85 ^{\circ}\text{C}$	101	℃
Median Lifetime (T <sub>M</sub> )	Toase = 00 0	>1.0E+7	Hrs

#### Notes:

#### **Median Lifetime**

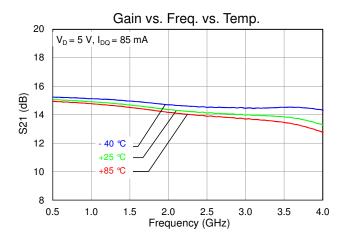


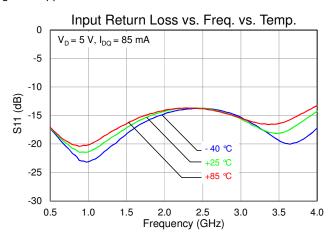
<sup>1.</sup> Thermal resistance measured to back of carrier plate. MMIC mounted on 8 mils thick CDA194 carrier using 84-1 epoxy.

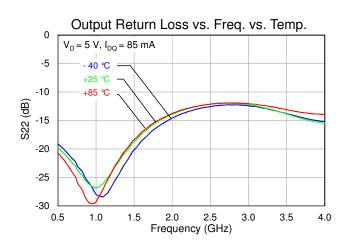


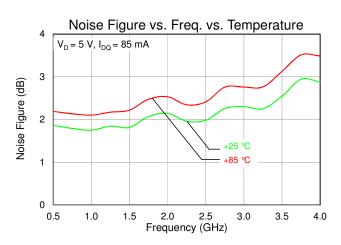
# Typical Performance

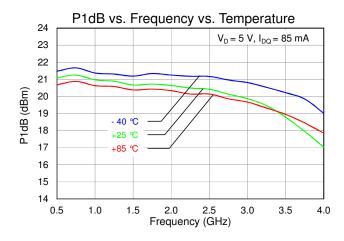
Test conditions unless otherwise noted: 25 °C, V<sub>D</sub> = 5 V, tested using EVB application circuit

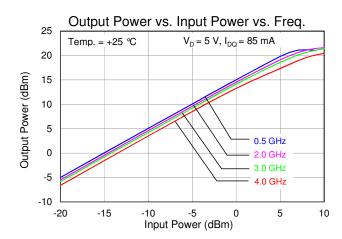








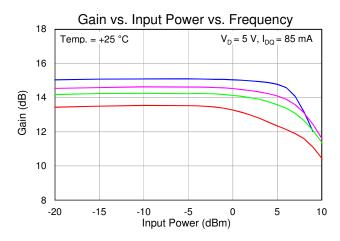


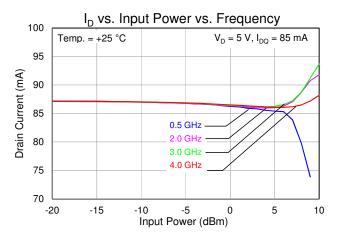


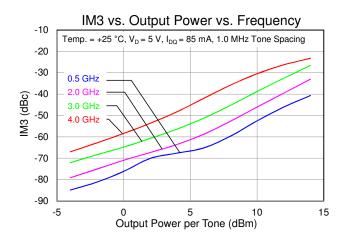


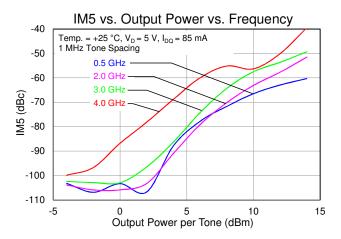
# **Typical Performance**

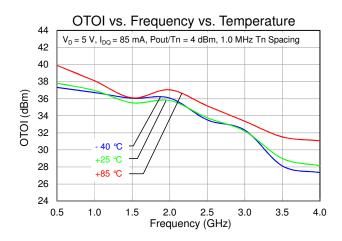
Test conditions unless otherwise noted: 25 °C, V<sub>D</sub> = 5 V, tested using EVB application circuit





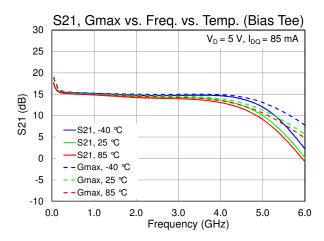


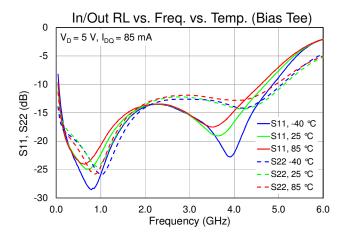


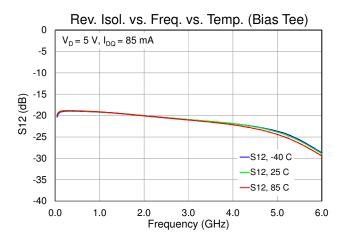




# **Typical Performance**

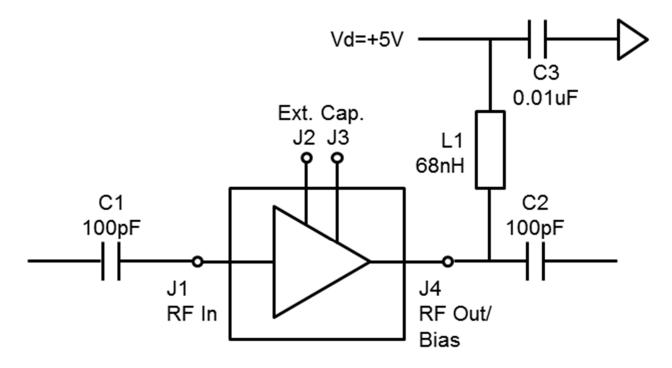








## **Application Circuit**



Note: Optional external capacitor can be connected between J 2 and J3 to extend functional bandwidth down to 50 MHz.

### **Bias-up Procedure**

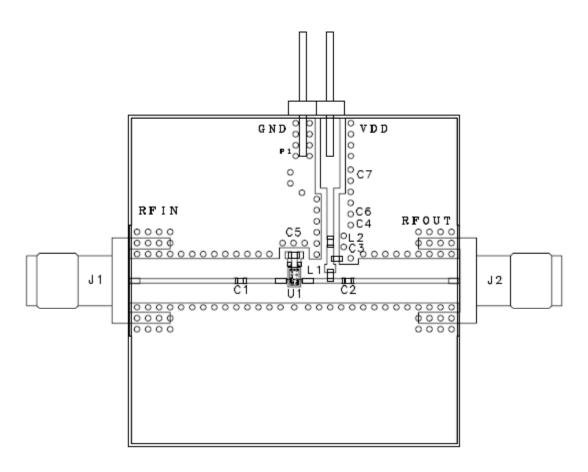
- 1. Set ID limit to 140 mA, set VD to 0 V
- 2. Apply +5 V to RF Output/Bias (part self-biases to appropriate lds value)
- 3. Apply RF signal

#### **Bias-down Procedure**

- 1. Turn off RF signal
- 2. Reduce  $V_D$  to 0 V
- 3. Turn off V<sub>D</sub> supply



## **Assembly Drawing**

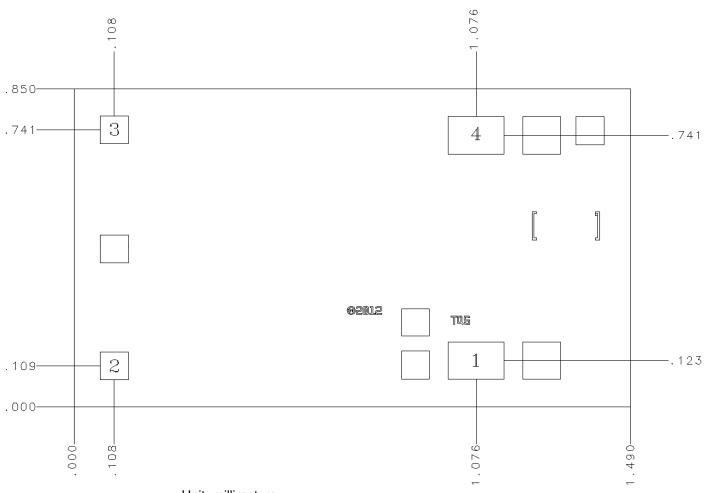


#### Notes:

- 1. PCB material: Rogers 4003, 8 mil thick, 0.5 oz. copper.
- 2. RF Connector: Gigalane PSF-S01 SMA
- 3. 0402 Components: C1,C2=100pF, L1=68 nH coil, L2=0 Ohm Jumper, C3=0.01uF
- 4. Capacitor C5 can be added to extend the low frequency cutoff to 50 MHz. Customer to optimize the capacitor value.



# **Mechanical Drawing**



Unit: millimeters Thickness: 0.085

Die x, y size tolerance: +/- 0.050

Chip edge to bond pad dimensions are shown to center of pad

Ground is backside of die

Bond Pad	Symbol	Pad Size (mm)	Description
1	RF Input	0.150 x 0.100	RF Input matched to 50 Ohms, not DC blocked
2	(Opt.) Ext. Cap	0.075 x 0.075	Connect ext. cap to increase lower end bandwidth
3	(Opt.) Ext. Cap	0.075 x 0.075	Connect ext. cap to increase lower end bandwidth
4	RF Output/Bias	0.150 x 0.100	RF Output matched to 50 Ohms, not DC blocked, apply device bias





### **Assembly Notes**

Component placement and adhesive attachment assembly notes:

- Vacuum pencils and/or vacuum collets are the preferred method of pick up.
- The force impact is critical during auto placement.
- Organic attachment (i.e. epoxy) can be used in low-power applications.
- Curing should be done in a convection oven; proper exhaust is a safety concern.

#### Interconnect process assembly notes:

- Thermosonic ball bonding is the preferred interconnect technique.
- Force, time, and ultrasonics are critical parameters.
- Aluminum wire should not be used.
- Devices with small pad sizes should be bonded with 0.0007-inch wire.



### **Product Compliance Information**

#### **ESD Sensitivity Ratings**



Caution! ESD-Sensitive Device

ESD Rating: Class 1A

Value: Passes ≥ 250 V to < 500 V
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

#### **ECCN**

US Department of Commerce: EAR99

#### Die Attach

Die attach should be accomplished with conductive epoxy only. Eutectic attach is not recommended.

#### **RoHS Compliance**

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>0<sub>2</sub>) Free
- PFOS Free
- SVHC Free

#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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